

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: J. TANAKA et al et al
Serial No. 10/179,214
Filed: June 26, 2002

Group Art Unit: 2815
Examiner: S. Clark
For: RESIN-ENCAPSULATED SEMICONDUCTOR
APPARATUS AND PROCESS FOR ITS
FABRICATION

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Alexandria, VA 22314

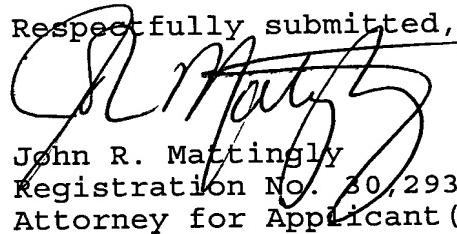
Sir:

In accordance with the duty of disclosure, Applicants inform the Examiner of the documents cited during prosecution of the parent application, USSN 10/179,214.

This is a continuation application of U.S. Serial No. 10/179,214, filed on June 26, 2002, which is a continuation application of U.S. Serial No. 09/969,847, filed October 4, 2001, now U.S. Patent No. 6,465,827, which is a continuation application of U.S. Serial No. 09/689,802, filed October 13, 2000, now U.S. Patent No. 6,441,416, which is a continuation application of U.S. Serial No. 09/665,062, filed September 19, 2000, abandoned, which is a divisional application of U.S. Serial No. 09/012,104, filed January 22, 1998, now U.S. Patent No. 6,147,374. This application is related to application Serial No. 09/969,848, filed October 4, 2001, now U.S. Patent No. 6,525,359, from which priority is claimed under 35 U.S.C. § 120.

The applicants request the Examiner to initial and return a copy of the attached PTO-1449 form as an indication that the references have been considered.

Respectfully submitted,



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Date: September 29, 2003

FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO.
LIST OF DOCUMENTS CITED BY APPLICANT <i>(Use several sheets if necessary)</i>		APPLICANT J. TANAKA et al	
		FILING DATE 09/29/03	GROUP 2815

U.S. PATENT DOCUMENTS

* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
	AA	5,563,762	10/1996	Leung et al			
	AB	5,117,272	05-1992	Nomura et al			
	AC	5,310,863	05-1994	Sachdev			
	AD	6,071,755	06-2000	Baba et al			
	AE	6,106,906	08-2000	Matsuda et al			
	AF	5,296,716	03-1994	Ovashinsky et al			
	AG	4,132,823	1/2/79	Blackwell et al			
	AH	6,465,827	10/2002	Tanaka et al			
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES <input type="checkbox"/> NO <input type="checkbox"/>
	AL	8-124917	05-1996	Japan			<input type="checkbox"/> <input type="checkbox"/>
	AM	7-278301	10-1995	Japan			<input type="checkbox"/> <input type="checkbox"/>
	AN	07-221259	8/18/95	Japan			<input type="checkbox"/> <input type="checkbox"/>
	AO	09-293837	11/11/97	Japan			<input type="checkbox"/> <input type="checkbox"/>
	AP						<input type="checkbox"/> <input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

AR		Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.
AS		Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992.
AT		Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.

EXAMINER _____ DATE CONSIDERED _____

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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	AM						<input type="checkbox"/> <input type="checkbox"/>
	AN						<input type="checkbox"/> <input type="checkbox"/>
	AO						<input type="checkbox"/> <input type="checkbox"/>
	AP						<input type="checkbox"/> <input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

AR		A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.
AS		Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.
AT		

EXAMINER	DATE CONSIDERED
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